

Applicant : Michael N. Perugini et al.
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Amendments to the Specification:

Please delete previous abstract at page 29 and add the following new abstract:

-- An intercoupling component for receiving an array of contacts includes a non-conductive substrate having a plurality of holes disposed on its upper surface and arranged in a predetermined footprint corresponding to the array of contacts. Contacts are disposed within the holes and a cavities, which may be open to air or filled with some other dielectric material, are disposed in the substrate between adjacent contacts. --